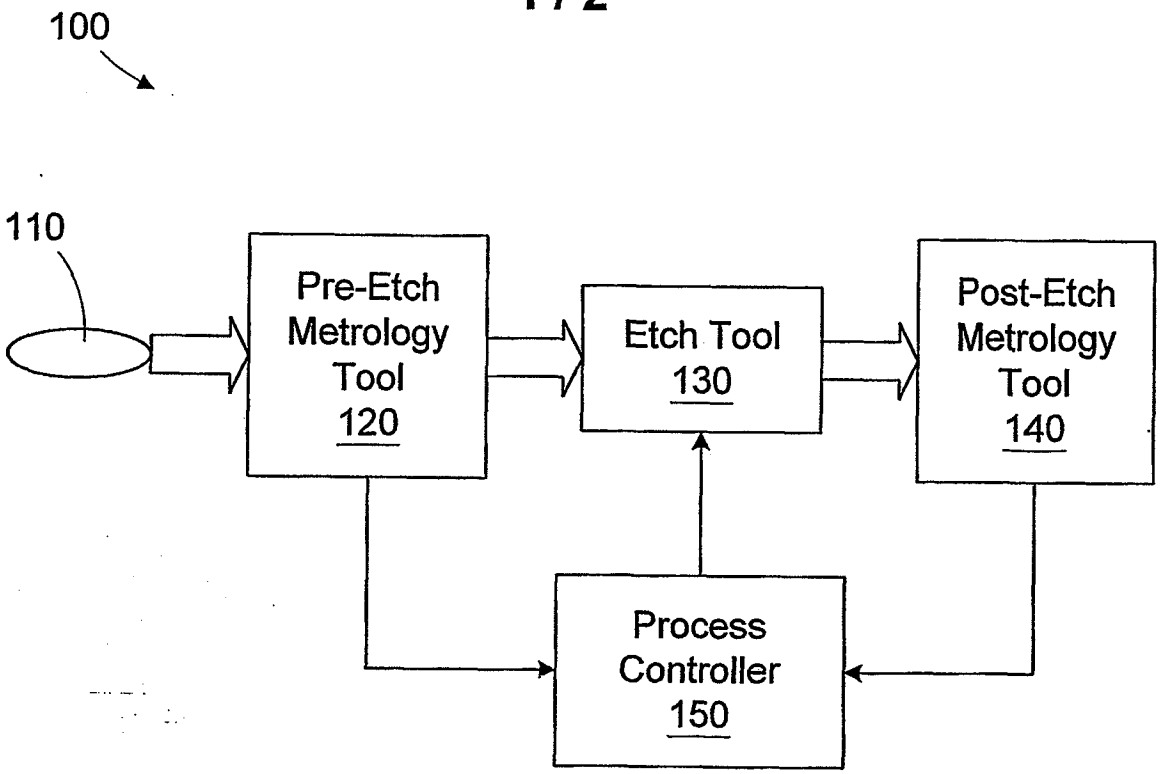


Figure 1

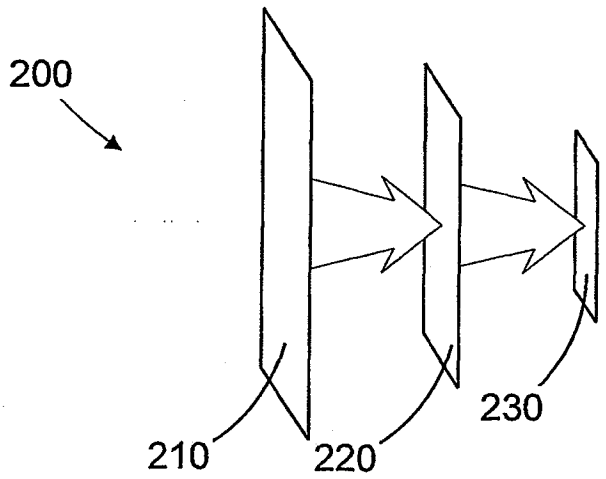


Figure 2

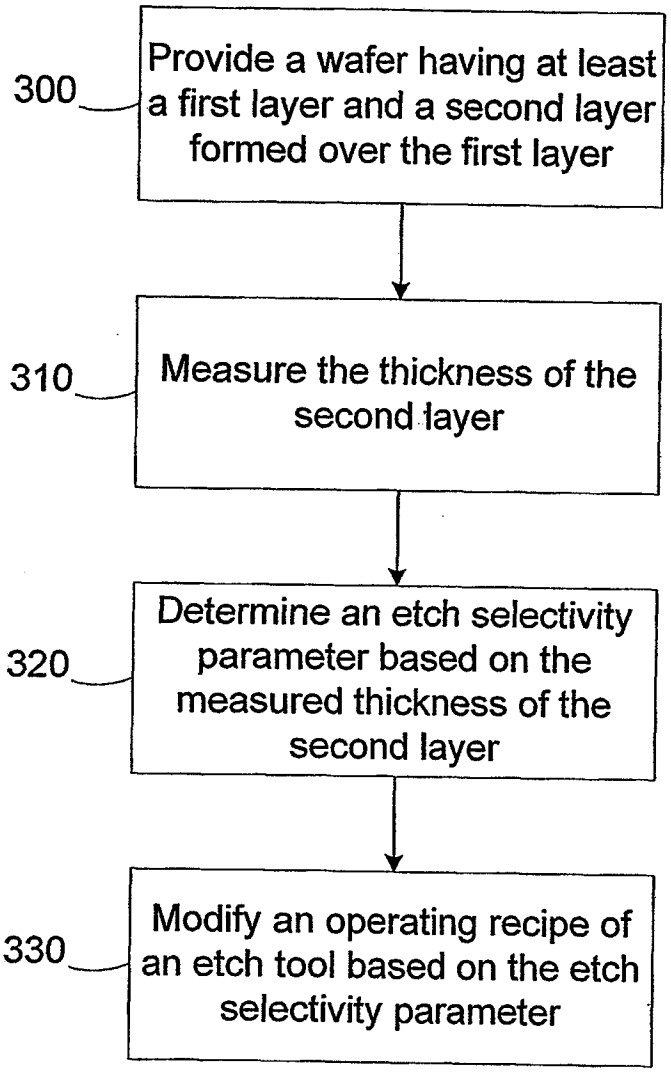

300
Provide a wafer having at least a first layer and a second layer formed over the first layer
310
Measure the thickness of the second layer
320
Determine an etch selectivity parameter based on the measured thickness of the second layer
330
Modify an operating recipe of an etch tool based on the etch selectivity parameter

Figure 3